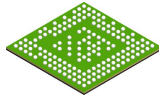


**DATA BOOK
PACKAGE OUTLINE**

DRAFTER:	T. LEQUANG	DATE:	11/09/2015			DIMENSIONS IN MILLIMETERS			
DESIGNER:		DATE:		 TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS		CODE IDENTITY NUMBER 01295			
CHECKER:	T. LEQUANG & V. PAKU	DATE:	10/18/2016						
ENGINEER:	G. MORRISON	DATE:	10/18/2016						
APPROVED:	E. REY	DATE:	10/18/2016						
RELEASED:	WDM	DATE:	10/18/2016						
				ePOD, ABL0161A / FCBGA, 161 BALL, 0.65 MM PITCH					
TEMPLATE INFO:		DATE:		SCALE	SIZE	4222493		REV	PAGE
EDGE# 4218519		04/07/2016		NTS	A			B	1 OF 5

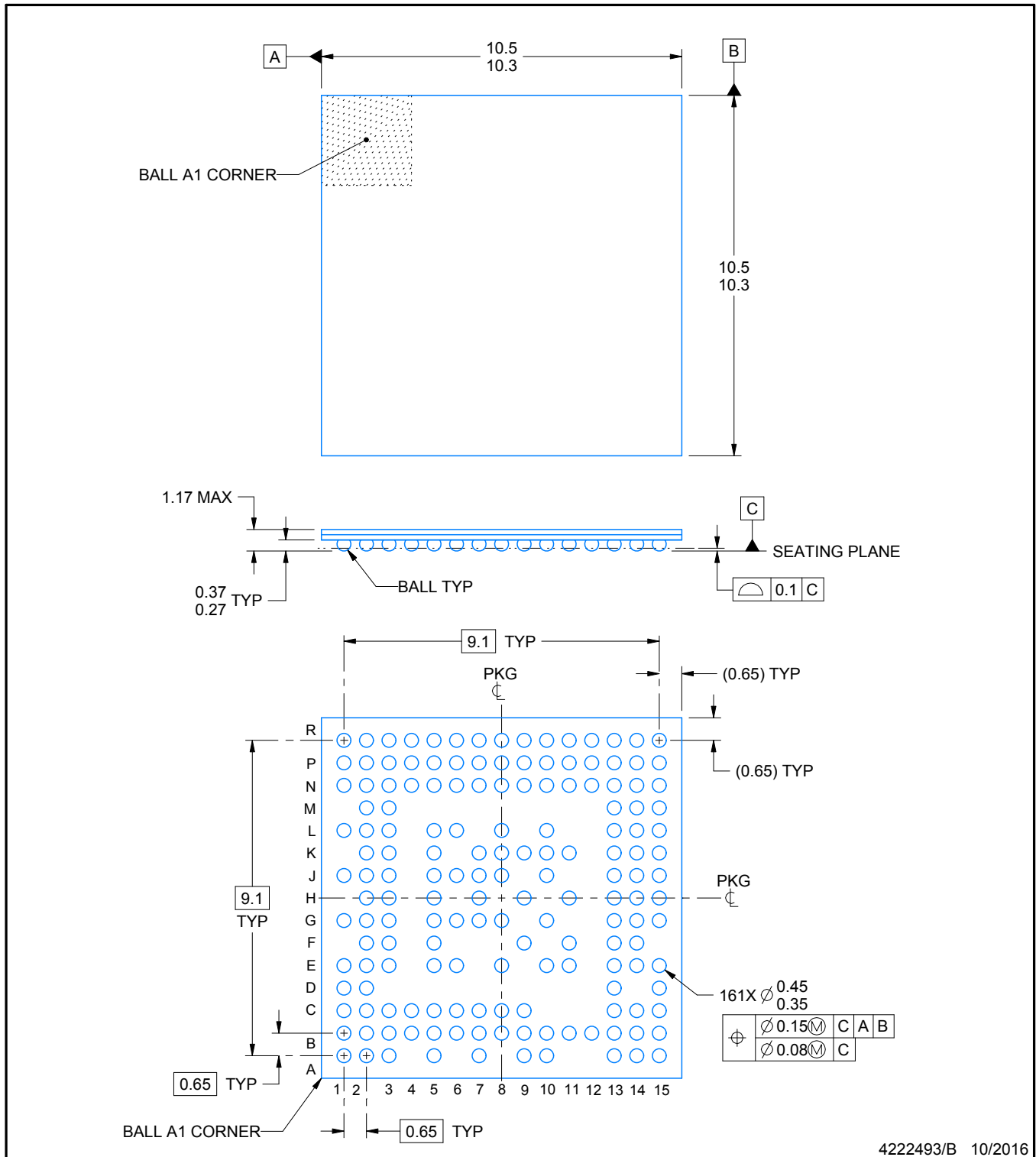


PACKAGE OUTLINE

ABL0161A

FCBGA - 1.17 mm max height

PLASTIC BALL GRID ARRAY



NOTES:

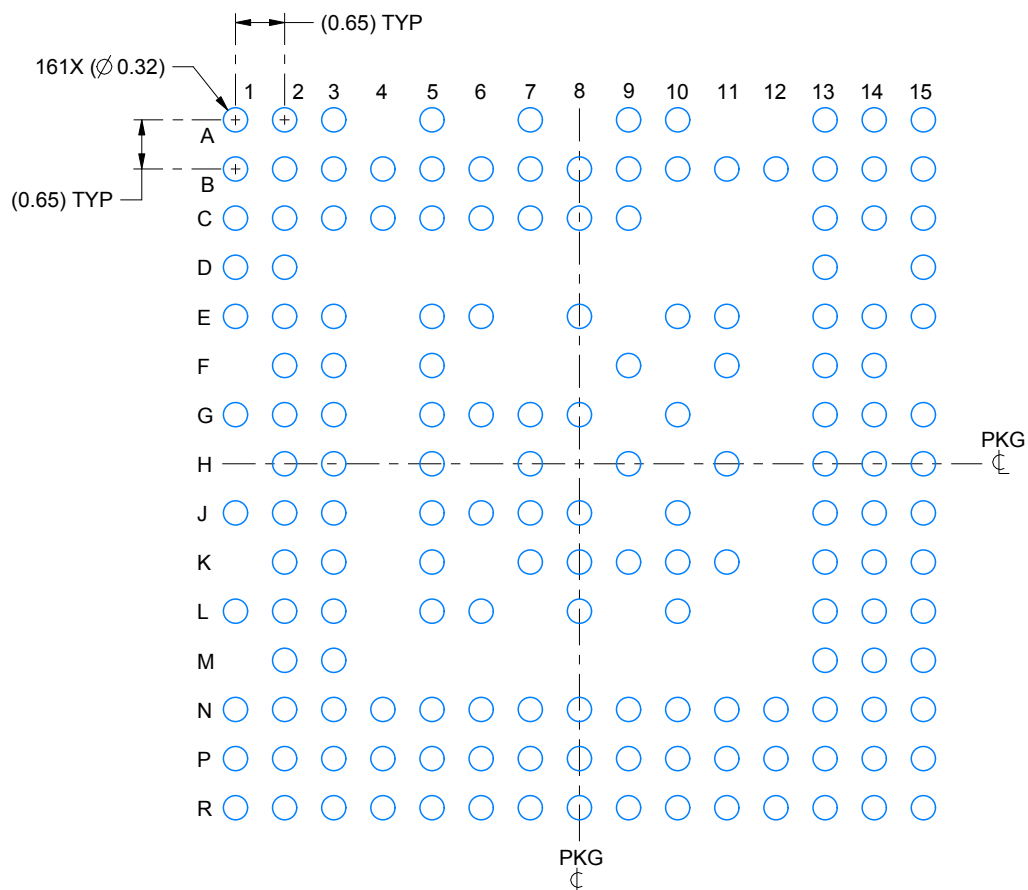
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

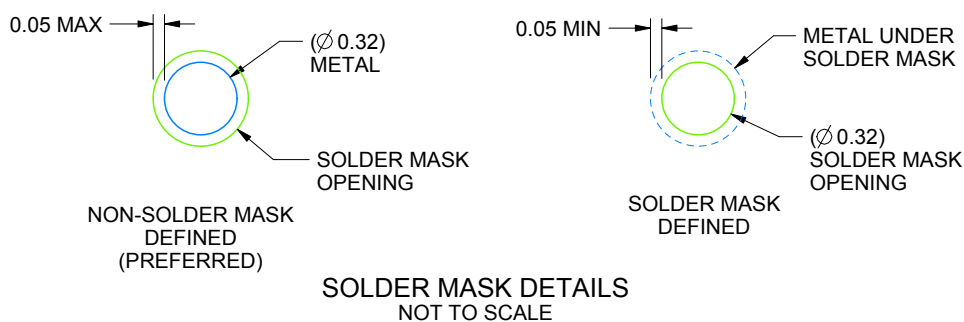
ABL0161A

FCBGA - 1.17 mm max height

PLASTIC BALL GRID ARRAY



LAND PATTERN EXAMPLE
SCALE:10X



4222493/B 10/2016

NOTES: (continued)

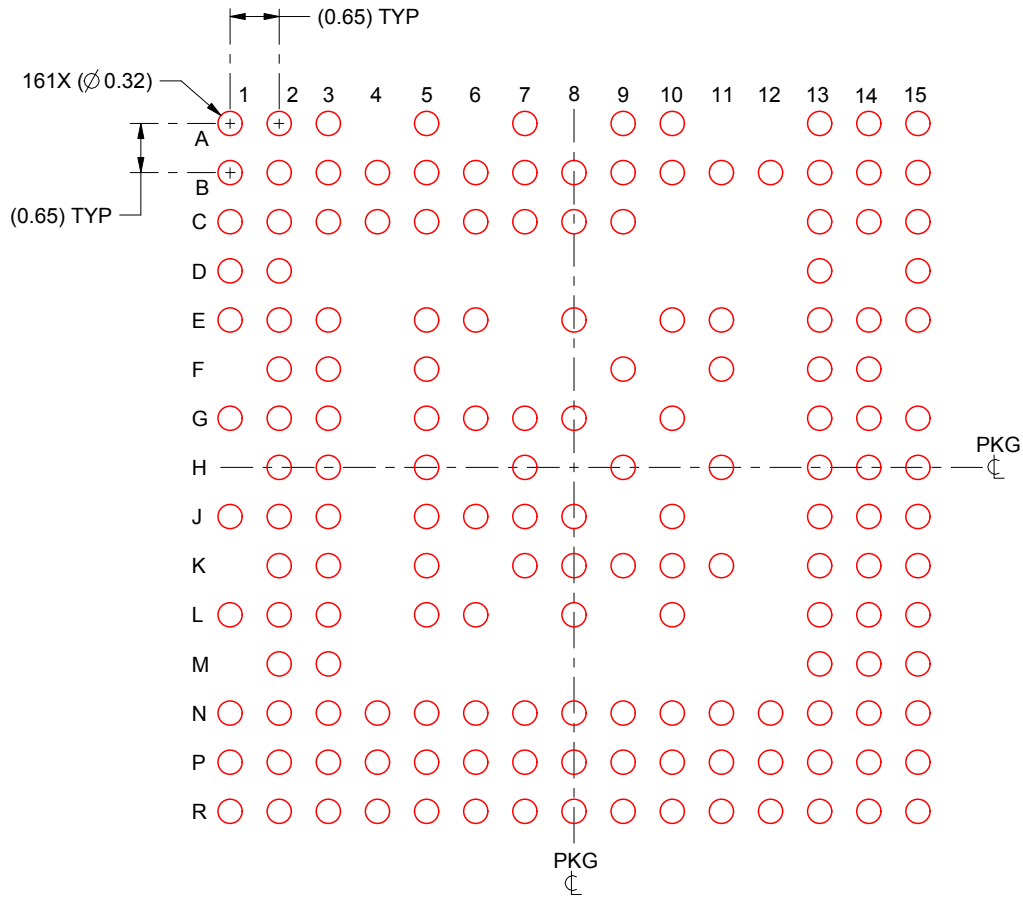
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 (www.ti.com/lit/spraa99).

EXAMPLE STENCIL DESIGN

ABL0161A

FCBGA - 1.17 mm max height

PLASTIC BALL GRID ARRAY



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:10X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2153515	11/09/2015	G. MORRISON / T. LEQUANG
B	MAX HEIGHT WAS 1.2; SOLDER BALL HEIGHT WAS 0.21-0.37;	2161395	10/18/2016	G. MORRISON / K. SINCERBOX